

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 61 and 84-105.

Listing of Claims:

1-59. (Cancelled)

60. (Previously Presented) A planarizing machine for planarizing microelectronic-device substrate assemblies, comprising:

a support table;

a polishing pad on the support table, the polishing pad having a body, a planarizing surface on the body, and a plurality of abrasive particles fixedly attached to the body at the planarizing surface;

a carrier assembly having a carrier head configured to hold a substrate assembly and a drive mechanism attached to the carrier head to move the carrier relative to the polishing pad; and

a non-abrasive lubricating planarizing solution without abrasive particles on the polishing pad, the lubricating planarizing solution having a viscosity of at least approximately 4 to approximately 100 cP, wherein the non-abrasive lubricating planarizing solution further comprises homopolymers and copolymers of acrylic acid crosslinked with a polyalkenyl polyether.

61. (Canceled)

62. (Previously Presented) The planarizing machine of claim 60, wherein the non-abrasive lubricating planarizing solution further comprises glycerol mixed into a non-abrasive solution comprising an aqueous solution of ammonia.

63. (Previously Presented) The planarizing machine of claim 62, wherein the non-abrasive lubricating planarizing solution has a viscosity of at least approximately 10 to approximately 20 cP.

64. (Cancelled)

65. (Previously Presented) The planarizing machine of claim 60, wherein the non-abrasive lubricating planarizing solution has a viscosity of at least approximately 10 to approximately 20 cP.

66-75. (Cancelled)

76. (Previously Presented) The planarizing machine of claim 60, wherein the non-abrasive lubricating planarizing solution is mixed into a non-abrasive solution comprising an aqueous solution of ammonia.

77. (Previously Presented) The planarizing machine of claim 76, wherein the non-abrasive lubricating planarizing solution has a viscosity of at least approximately 10 to approximately 100 cP.

78. (Previously Presented) The planarizing machine of claim 60, wherein the homopolymers and copolymers of acrylic acid crosslinked with a polyalkenyl polyether is mixed into a non-abrasive solution comprising an aqueous solution of ammonia, the homopolymers and copolymers of acrylic acid crosslinked with a polyalkenyl polyether being present in an amount 0.25% by weight and the non-abrasive solution being present in an amount 99.75% by weight.

79. (Previously Presented) The planarizing machine of claim 78, wherein the non-abrasive lubricating planarizing solution has a viscosity of at least approximately 10 to approximately 100 cP.

80-105. (Cancelled)

Amendments to the Drawings:

The attached sheet of drawings includes changes to Fig. 3. This sheet, which includes Figs. 1-4, replaces the original sheet, including Figs. 1-4. In Fig. 3, the second occurrence of reference numeral 113 has been changed to 114 and reference numeral 114 has been changed to 115.

Attachments: Replacement Sheet
Annotated Sheet Showing Changes